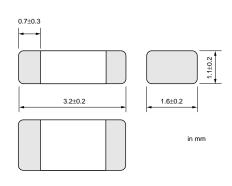
Data Sheet

Chip EMIFIL[®] Inductor Type Chip Ferrite Beads

BLM31P Series (1206 Size)

Dimension



Equivalent Circuit

()

(Resistance element becomes dominant at high frequencies.)

Packaging

Code	Packaging	Minimum Quantity	
L	180mm Embossed Tape	3000	
к	330mm Embossed Tape	10000	
В	Bulk(Bag)	1000	

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance(max.)	Operating Temperature Range
BLM31PG330SN1	33ohm±25%	-	6000mA	0.01ohm	-55°C to +125°C
BLM31PG500SN1	50ohm(Typ.)	-	3000mA	0.025ohm	-55°C to +125°C
BLM31PG121SN1	120ohm±25%	-	3000mA	0.025ohm	-55°C to +125°C
BLM31PG391SN1	390ohm±25%	-	2000mA	0.05ohm	-55°C to +125°C
BLM31PG601SN1	600ohm±25%	-	1500mA	0.09ohm	-55°C to +125°C

Number of Circuits: 1

Continued on the following page.

1

• This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

A Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.

2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.





Continued from the preceding page.

■ Notice (Rating)

In operating temperature exceeding +85°C, derating of

■ Impedance-Frequency Characteristics (Main)

BLM31PG601SN

BLM31PG391SN1

BLM31PG121SN1

10

100

Frequency (MHz)

700

600

500

300

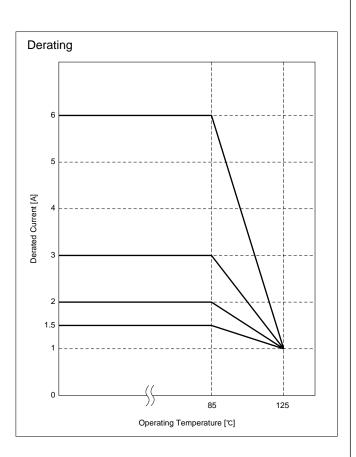
200 100

0

mpedance (Ω) 400

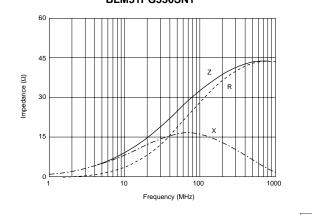
current is necessary for BLM31PG series.

Please apply the derating curve shown in chart according to the operating temperature.



2

Impedance-Frequency Characteristics BLM31PG330SN1



Continued on the following page.

This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

1000

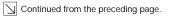
∆ Note:

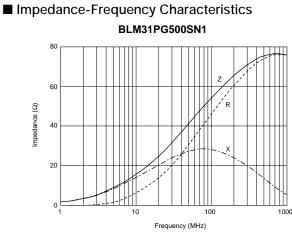
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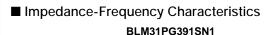
2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

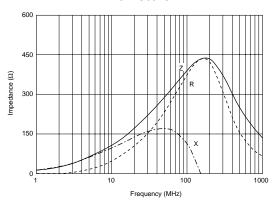






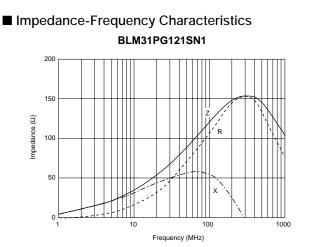






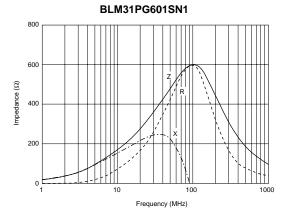
■ ①Caution/Notice

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.



3

Impedance-Frequency Characteristics





Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

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